

January 2008

# 74AC00, 74ACT00 Quad 2-Input NAND Gate

### **Features**

### **General Description**

The AC00/ACT00 contains four, 2-input NAND gates.

- I<sub>CC</sub> reduced by 50%
- Outputs source/sink 24mA
- ACT00 has TTL-compatible inputs

### **Ordering Information**

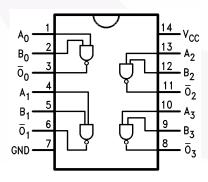
Order Number	Package Number	Package Description
74AC00SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74AC00SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC00MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC00PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
74ACT00SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74ACT00SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACT00MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ACT00PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



All packages are lead free per JEDEC: J-STD-020B standard.

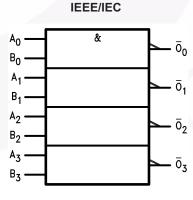
## **Connection Diagram**



## **Pin Description**

Pin Names	Description
A <sub>n</sub> , B <sub>n</sub>	Inputs
Ōn	Outputs

## **Logic Symbol**



### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter Rating		
V <sub>CC</sub>	Supply Voltage	-0.5V to +7.0V	
I <sub>IK</sub>	DC Input Diode Current		
	$V_{I} = -0.5V$	–20mA	
	$V_{I} = V_{CC} + 0.5$	+20mA	
V <sub>I</sub>	DC Input Voltage	-0.5V to V <sub>CC</sub> + 0.5V	
I <sub>OK</sub>	DC Output Diode Current		
	$V_{O} = -0.5V$	–20mA	
	$V_{O} = V_{CC} + 0.5V$	+20mA	
Vo	DC Output Voltage	-0.5V to V <sub>CC</sub> + 0.5V	
Io	DC Output Source or Sink Current	±50mA	
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current per Output Pin	±50mA	
T <sub>STG</sub>	Storage Temperature	−65°C to +150°C	
T <sub>J</sub>	Junction Temperature	140°C	

### **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating			
V <sub>CC</sub>	Supply Voltage				
	AC	2.0V to 6.0V			
	ACT	4.5V to 5.5V			
VI	Input Voltage 0V to				
V <sub>O</sub>	Output Voltage 0V to				
T <sub>A</sub>	Operating Temperature -40°C to +85°				
ΔV / Δt	Minimum Input Edge Rate, AC Devices: 125mV/n				
	V <sub>IN</sub> from 30% to 70% of V <sub>CC</sub> , V <sub>CC</sub> @ 3.3V, 4.5V, 5.5V				
ΔV / Δt	Minimum Input Edge Rate, ACT Devices: 125mV/n				
	V <sub>IN</sub> from 0.8V to 2.0V, V <sub>CC</sub> @ 4.5V, 5.5V				

## **DC Electrical Characteristics for AC**

	$V_{CC}$ $T_A = +25^{\circ}C$		+25°C	T <sub>A</sub> = -40°C to +85°C			
Symbol	Parameter	(V)	Conditions	Тур.	G	uaranteed Limits	Units
V <sub>IH</sub>	Minimum HIGH Level	3.0	$V_{OUT} = 0.1V$	1.5	2.1	2.1	V
	Input Voltage	4.5	or V <sub>CC</sub> – 0.1V	2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V <sub>IL</sub>	Maximum LOW Level	3.0	$V_{OUT} = 0.1V$	1.5	0.9	0.9	V
	Input Voltage	4.5	or V <sub>CC</sub> – 0.1V	2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V <sub>OH</sub>	Minimum HIGH Level	3.0	$I_{OUT} = -50\mu A$	2.99	2.9	2.9	V
	Output Voltage	4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -12\text{mA}$		2.56	2.46	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(1)}$		4.86	4.76	
V <sub>OL</sub>	Maximum LOW Level	3.0	$I_{OUT} = 50\mu A$	0.002	0.1	0.1	V
	Output Voltage	4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 12\text{mA}$		0.36	0.44	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(1)}$		0.36	0.44	
I <sub>IN</sub> <sup>(3)</sup>	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$ , GND		±0.1	±1.0	μA
I <sub>OLD</sub>	Minimum Dynamic	5.5	V <sub>OLD</sub> = 1.65V Max.			75	mA
I <sub>OHD</sub>	Output Current <sup>(2)</sup>	5.5	V <sub>OHD</sub> = 3.85V Min.			<b>–</b> 75	mA
I <sub>CC</sub> <sup>(3)</sup>	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		2.0	20.0	μA

#### Notes:

- 1. All outputs loaded; thresholds on input associated with output under test.
- 2. Maximum test duration 2.0ms, one output loaded at a time.
- 3.  $I_{IN}$  and  $I_{CC}$  @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V  $V_{CC}$ .

## **DC Electrical Characteristics for ACT**

		V <sub>CC</sub>		T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C	
Symbol	Parameter	(V)	Conditions	Тур.	0	Buaranteed Limits	Units
V <sub>IH</sub>	Minimum HIGH Level	4.5	$V_{OUT} = 0.1V$ or	1.5	2.0	2.0	V
	Input Voltage	5.5	V <sub>CC</sub> – 0.1V	1.5	2.0	2.0	
V <sub>IL</sub>	Maximum LOW Level	4.5	$V_{OUT} = 0.1V$ or	1.5	0.8	0.8	V
	Input Voltage	5.5	V <sub>CC</sub> – 0.1V	1.5	0.8	0.8	]
V <sub>OH</sub>	Minimum HIGH Level	4.5	$I_{OUT} = -50\mu A$	4.49	4.4	4.4	V
	Output Voltage	5.5		5.49	5.4	5.4	]
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(4)}$		4.86	4.76	
V <sub>OL</sub>	Maximum LOW Level	4.5	I <sub>OUT</sub> = 50μA	0.001	0.1	0.1	V
	Output Voltage	5.5		0.001	0.1	0.1	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(4)}$		0.36	0.44	
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$ , GND		±0.1	±1.0	μA
I <sub>CCT</sub>	Maximum I <sub>CC</sub> /Input	5.5	$V_I = V_{CC} - 2.1V$	0.6		1.5	mA
I <sub>OLD</sub>	Minimum Dynamic	5.5	V <sub>OLD</sub> = 1.65V Max.			75	mA
I <sub>OHD</sub>	Output Current <sup>(5)</sup>	5.5	V <sub>OHD</sub> = 3.85V Min.			<b>-</b> 75	mA
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		2.0	20.0	μA

#### Notes:

- 4. All outputs loaded; thresholds on input associated with output under test.
- 5. Maximum test duration 2.0ms, one output loaded at a time.

## **AC Electrical Characteristics for AC**

			T <sub>A</sub> = +25°C, C <sub>L</sub> = 50pF					
Symbol	Parameter	V <sub>CC</sub> (V) <sup>(6)</sup>	Min.	Тур.	Max.	Min.	Max.	Units
t <sub>PLH</sub>	Propagation Delay	3.3	2.0	7.0	9.5	2.0	10.0	ns
		5.0	1.5	6.0	8.0	1.5	8.5	
t <sub>PHL</sub>	Propagation Delay	3.3	1.5	5.5	8.0	1.0	8.5	ns
		5.0	1.5	4.5	6.5	1.0	7.0	

#### Note:

6. Voltage range 3.3 is  $3.3V \pm 0.3V$ . Voltage range 5.0 is  $5.0V \pm 0.5V$ .

## **AC Electrical Characteristics for ACT**

				<sub>λ</sub> = +25° C <sub>L</sub> = 50p		T <sub>A</sub> = -40°C C <sub>L</sub> =	to +85°C, 50pF	
Symbol	Parameter	$V_{CC}(V)^{(7)}$	Min.	Тур.	Max.	Min.	Max.	Units
t <sub>PLH</sub>	Propagation Delay	5.0	1.5	5.5	9.0	1.0	9.5	ns
t <sub>PHL</sub>	Propagation Delay	5.0	1.5	4.0	7.0	1.0	8.0	ns

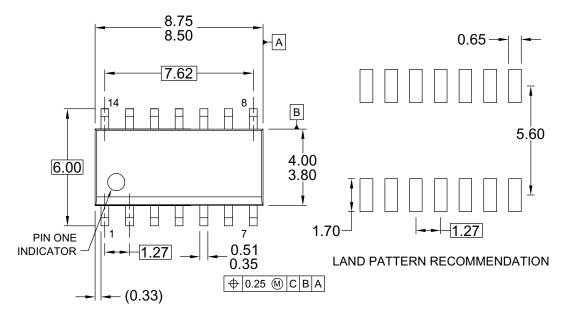
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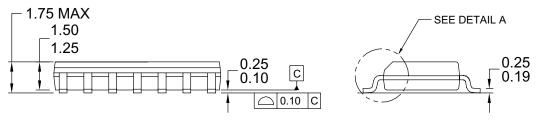
7. Voltage Range 5.0 is 5.0V ± 0.5V.

## Capacitance

Symbol	Parameter	Conditions	Тур.	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = OPEN	4.5	pF
C <sub>PD</sub>	Power Dissipation Capacitance	V <sub>CC</sub> = 5.0V	30.0	pF

### **Physical Dimensions**





NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
  B) ALL DIMENSIONS ARE IN MILLIMETERS.
  C) DIMENSIONS DO NOT INCLUDE MOLD.
  - C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
  - D) LANDPATTERN STANDARD: SOIC127P600X145-14M
  - E) DRAWING CONFORMS TO ASME Y14.5M-1994
  - F) DRAWING FILE NAME: M14AREV13

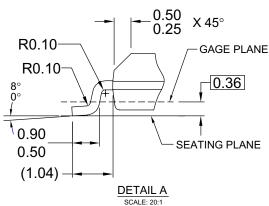


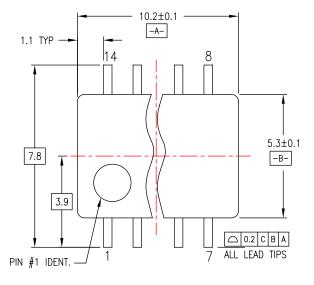
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

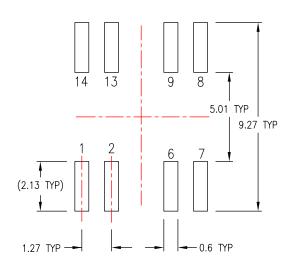
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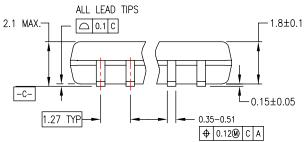
http://www.fairchildsemi.com/packaging/

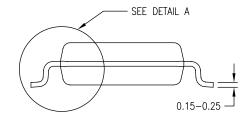
### Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATION



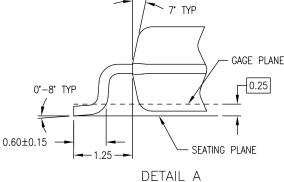


DIMENSIONS ARE IN MILLIMETERS

#### NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
  B. DIMENSIONS ARE IN MILLIMETERS.
  C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD

FLASH, AND TIE BAR EXTRUSIONS.



M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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### Physical Dimensions (Continued) 5.0±0.1 -A-0.65 0.43 TYP 6.4 4.4±0.1 -B-1.65 3.2 □ 0.2 C B A PIN #1 IDENT. 6.10 0.45 -LAND PATTERN RECOMMENDATION SEE DETAIL A ALL LEAD TIPS 0.90+0.15 1.2 MAX □ 0.1 C 0.09-0.20 -C-0.10±0.05 0.65 0.19 - 0.30⊕ |0.13\\(\) |A |B\(\) |C\(\) 12.00°TOP & BOTTOM R0.09 min GAGE PLANE 0.25 0°-8° NOTES: 0.6±0.1 A. CONFORMS TO JEDEC REGISTRATION MO-153, SEATING PLANE R0.09min VARIATION AB, REF NOTE 6 1 00 **B. DIMENSIONS ARE IN MILLIMETERS DETAIL A**

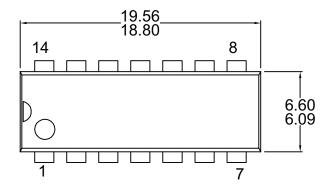
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

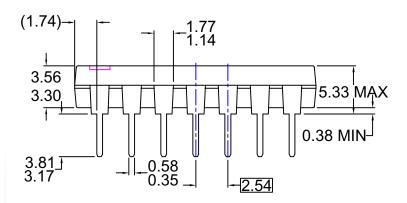
Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

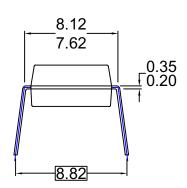
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### Physical Dimensions (Continued)







NOTES: UNLESS OTHERWISE SPECIFIED THIS PACKAGE CONFORMS TO

- A) JEDEC MS-001 VARIATION BA
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
  DIMENSIONS ARE EXCLUSIVE OF BURRS.
- C) MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5-1994
- E) DRAWING FILE NAME: MKT-N14AREV7

Figure 4. 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

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Datasheet Identification	Product Status	Definition
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Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

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